NL3S22S

USB 2.0 + Audio Switch

The NL3S22S is a double−pole/double−throw (DPDT) analog switch for routing high speed differential data and audio. The high−speed data path is compliant with High Speed USB 2.0, Full Speed USB 1.1, Low Speed USB 1.0 and any generic UART protocol. The multi−purpose audio path is capable of passing signals with negative voltages as low as 2 V below ground and features shunt resistors to reduce Pop and Click noise in the audio system.

Features

- V_{CC} Range: 2.7 V to 5.5 V
- Control Pins Compatible with 1.8 V Interfaces
- I_{CC}: 23 μA (Typ)
- ESD Performance: 4 kV HBM
- Available in1.4 mm x 1.8 mm UQFN10
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

High Speed Data Path

- Input Signal Range: 0 V to 3.7 V
- $R_{DS(on)}$: 5 Ω (Typ)
- C_{ON}: 4.5 pF (Typ)
- Data Rate: USB 2.0–Compliant – up to 480 Mbps

Audio Path

- Input Signal Range: −2.0 V to 2.0 V
- R_{DSON}: 3 Ω (Typ)
- $R_{ON(FLAT)}$: 0.002 Ω (Typ)
- THD: 0.002% (R_L = 16 Ω / V_{IS} = 0.4 V_{RMS})

Applications

- Smartphones
- Tablets
- USB 2.0 Hosts/Peripherals
- Audio / High−Speeds Data Switching

ON Semiconductor®

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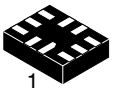
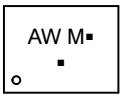
MARKING DIAGRAM



UQFN10
CASE 488AT



AW = Device Code
M = Date Code
▪ = Pb−Free Device

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NL3S22SMUTAG	UQFN10 (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

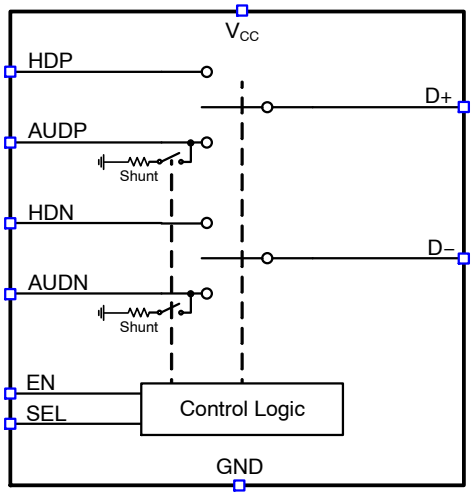


Figure 1. Block Diagram

FUNCTION TABLE

EN	SEL	Shunt Status	D+/D− Function
0	X	ON	No Connect
1	0	OFF	AUDP/AUDN
1	1	ON	HDP/HDN

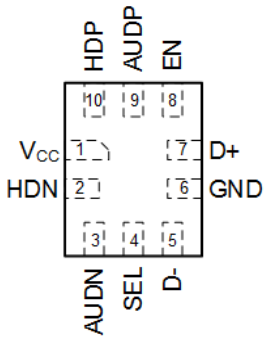


Figure 2. UQFN10 – Top Through View

PIN DESCRIPTION

Pin Name	Pin	Description
V_{CC}	1	Power Supply
HDN	2	High Speed Differential Data (−)
AUDN	3	Audio Signal (−)
SEL	4	Function Select
D−	5	Audio/Data Common I/O (−)
GND	6	Ground
D+	7	Audio/Data Common I/O (+)
EN	8	Chip Enable
AUDP	9	Audio Signal (+)
HDP	10	High Speed Differential Data (+)

MAXIMUM RATINGS

Rating	Symbol		Value	Unit
V_{CC}	Positive DC Supply Voltage		−0.3 to +6	V
V_{IS}	Analog Input/Output Voltage	HDP, HDN	−0.3 to +5.5	V
		AUDP, AUDN	−2.5 to V_{CC} + 0.3	
		D+, D−	−2.5 to +5.5	
V_{IN}	Digital Control Pin Voltage on EN, SEL		−0.3 to V_{CC} + 0.3	V
T_s	Storage Temperature		−55 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 seconds		260	°C
T_J	Junction Temperature Under Bias		150	°C
MSL	Moisture Sensitivity (Note 1)		Level 1	
I_{LU}	Latchup Current (Note 2)		±100	mA
ESD	ESD Protection (Note 3)	Human Body Model	4000	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Moisture Sensitivity Level (MSL): 1 per IPC/JEDEC standard: J−STD−020A.
2. Latch up Current Maximum Rating: ±100 mA per JEDEC standard: JESD78.
3. This device series contains ESD protection and passes the following tests:
   Human Body Model (HBM) ±4.0 kV per JEDEC standard: JESD22−A114 for all pins.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V_{CCEN}	Positive DC Supply Voltage		2.7	5.5	V
V_{IS}	Switch Input / Output Voltage (Note 4)	HDP, HDN	0	3.7	V
		AUDP, AUDN	−2.0	2.0	
		D+, D−	−2.0	3.7	
V_{IN}	Digital Control Input Voltage		GND	V_{CC}	V
T_A	Operating Temperature Range		−40	+85	°C

4. f the audio channel is not in use, it is recommended that no signals are applied on the audio inputs AUDN and AUDP.

DC ELECTRICAL CHARACTERISTICS (Typical values are at V_{CC} = +3.6 V and T_A = +25 °C)

Symbol	Parameter	Test Conditions	V_{CC} (V)	−40 °C to 85 °C			Unit
				Min	Typ	Max	
POWER SUPPLY							
I_{CC}	Supply Current	I_{IS} = 0 mA	4.2	–	23	105	μA
Control Logic (EN, SEL)							
V_{IH}	Input High Voltage		4.2	1.5	–	–	V
			3.6	1.4	–	–	
			2.7	1.3	–	–	
V_{IL}	Input Low Voltage		4.2	–	–	0.4	V
			3.6	–	–	0.4	
			2.7	–	–	0.4	
V_{IHYS}	Input Hysteresis		2.7 – 5.5	–	250	–	mV
I_{IN}	Leakage Current		2.7 – 5.5	–	–	±150	nA
AUDIO SWITCH (AUDP/AUDN ↔ D+/D−)							
R_{ON}	ON−Resistance	V_{IS} = −2.0 V to 2.0 V, I_{IS} = 50 mA	3.0	–	3	5	Ω
ΔR_{ON}	ON−Resistance Matching Between Channels	V_{IS} = −2.0 V to 2.0 V, I_{IS} = 50 mA	3.0	–	0.05	–	Ω
$R_{FLAT(ON)}$	ON Resistance Flatness	V_{IS} = −2.0 V to 2.0 V, I_{IS} = 50 mA	3.0	–	0.002	–	Ω
R_{SH}	Shunt Resistance		3.6	–	125	200	Ω
DATA SWITCH (HDP/HDN ↔ D+/D−)							
R_{ON}	ON−Resistance	V_{IS} = 0 V to 1.7 V, I_{IS} = 15 mA	3.0	–	5	7.5	Ω
ΔR_{ON}	ON−Resistance Matching Between Channels	V_{IS} = 0 V to 1.7 V, I_{IS} = 15 mA	3.0	–	0.02	–	Ω
$R_{FLAT(ON)}$	ON Resistance Flatness	V_{IS} = 0 V to 1.7 V, I_{IS} = 15 mA	3.0	–	0.003	–	Ω
$I_{SW(OFF)}$	OFF−State Leakage	V_{IS} = 0 V to 3.6	3.6	–	–	200	nA
$I_{SW(ON)}$	ON−State Leakage	V_{IS} = 0 V to 3.6	3.6	–	–	±200	nA

AC ELECTRICAL CHARACTERISTICS (Typical values are at V_{CC} = +3.6 V and T_A = +25 °C)

Symbol	Parameter	Test Conditions	V_{CC} (V)	−40 °C to 85 °C			Unit
				Min	Typ	Max	
AUDIO SWITCH (AUDP/AUDN ↔ D+/D−)							
THD	Audio THD	f = 20 Hz to 20 kHz, V_{IS} = 0.4 V_{RMS}, DC Bias = 0 V, R_L = 16 Ω	2.7 − 5.5	−	0.002	−	%
PSRR	Power Supply Ripple Rejection	From V_{CC} unto AUDP/AUDN, f = 217 Hz, R_L = 16 Ω	2.7 − 5.5	−	118	−	dB
DATA SWITCH (HDP/HDN ↔ D+/D−)							
C_{ON}	Equivalent ON−Capacitance	Switch ON, f = 1 MHz	3.6	−	4.84	−	pF
C_{OFF}	Equivalent OFF−Capacitance	Switch OFF, f = 1 MHz	3.6	−	2.06	−	pF
D_{IL}	Differential Insertion Loss	f = 10 MHz	2.7 − 5.5	−	−0.42	−	dB
		f = 800 MHz	2.7 − 5.5	−	−1.89	−	
		f = 1.1 GHz	2.7 − 5.5	−	−3.01	−	
D_{ISO}	Differential Off−Isolation	f = 10 MHz	2.7 − 5.5	−	−60	−	dB
		f = 800 MHz	2.7 − 5.5	−	−15	−	
		f = 1.1 GHz	2.7 − 5.5	−	−15	−	
D_{CTK}	Differential Crosstalk	f = 10 MHz	2.7 − 5.5	−	−67	−	dB
		f = 800 MHz	2.7 − 5.5	−	−23	−	
		f = 1.1 GHz	2.7 − 5.5	−	−19	−	
PSRR	Power Supply Ripple Rejection	From V_{CC} unto D+/D−, f = 217 Hz, R_L = 50 Ω	2.7 − 5.5	−	108	−	dB
DYNAMIC TIMING							
t_{PD}	Propagation Delay (Notes 5 and 6)	V_{NOn} or V_{NCn} = 0V, R_L = 50 Ω,	2.7 − 5.5	−	0.25	−	ns
t_{ON}	Turn−On Time	V_{IS} = 1 V, R_L = 50 Ω, C_L = 7 pF (fixture only)	2.7 − 5.5				µs
		EN or SEL to AUDP/AUDN		−	2.2	−	
		EN or SEL to HDP/HDN		−	6.2	−	
t_{OFF}	Turn−Off Time	V_{IS} = 1 V, R_L = 50 Ω, C_L = 7 pF (fixture only)	2.7 − 5.5				ns
		EN or SEL to AUDP/AUDN		−	67	−	
		EN or SEL to HDP/HDN		−	1200	−	
$t_{sk(b-b)}$	Bit to bit skew	Within the same differential channel	2.7 − 5.5	−	5	−	ps
$t_{sk(ch-ch)}$	Channel to channel skew	Maximum skew between all channels	2.7 − 5.5	−	5	−	ps

5. Guaranteed by design.
6. No other delays than the RC network formed by the load resistance and the load capacitance of the switch are added on the bus. For a 10 pF load, this delay is 5 ns which is much smaller than rise and fall time of typical driving systems. Propagation delays on the bus are determined by the driving circuit on the driving side and its interactions with the load of the driven side.

PARAMETER MEASUREMENT INFORMATION

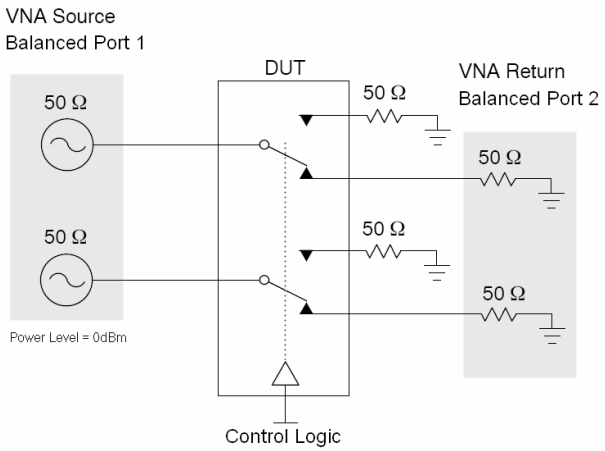


Figure 3. Differential Insertion Loss (S_{DD21})

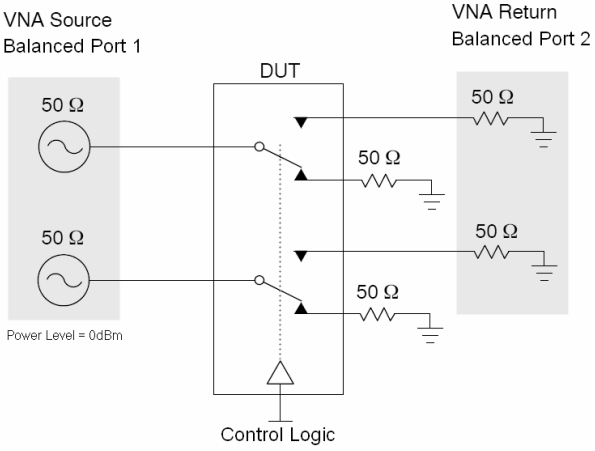


Figure 4. Differential Off Isolation (S_{DD21})

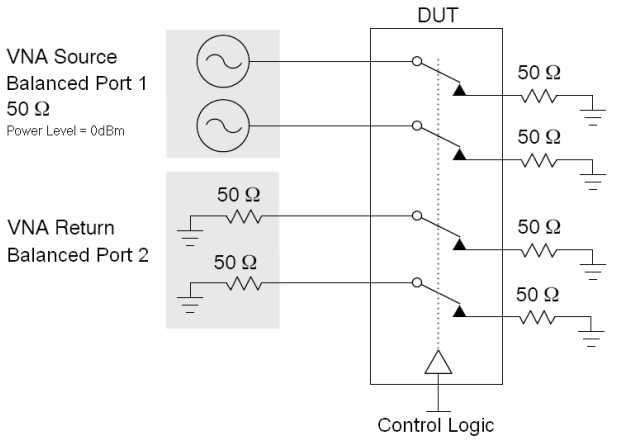
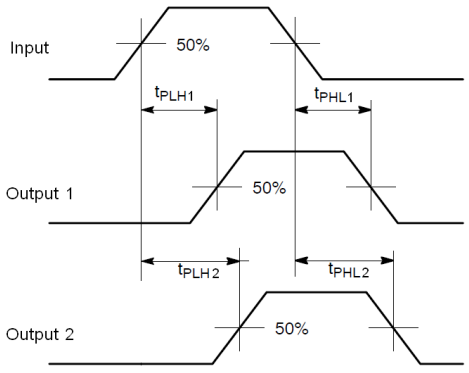
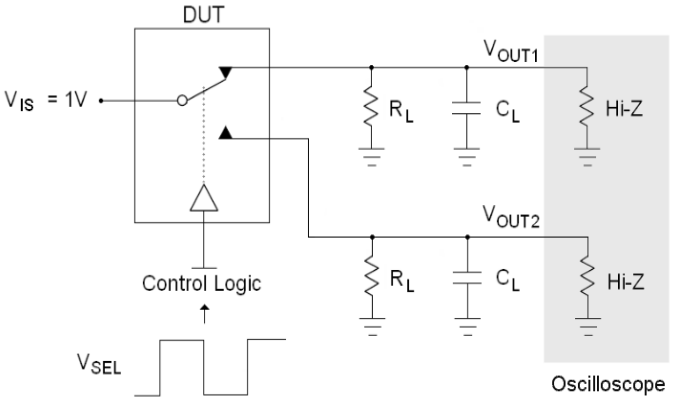


Figure 5. Differential Crosstalk (S_{DD21})



$t_{skew} = |t_{PLH1}\text{-}t_{PLH2}|$ or $|t_{PHL1}\text{-}t_{PHL2}|$

Figure 6. Bit−to−Bit and Channel−to−Channel Skew



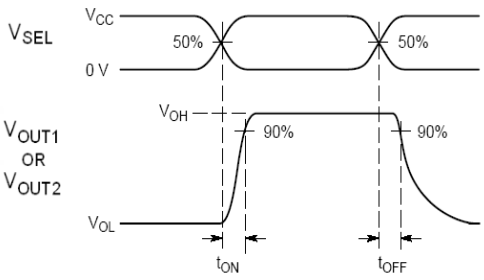


Figure 7. t_{ON} and t_{OFF}

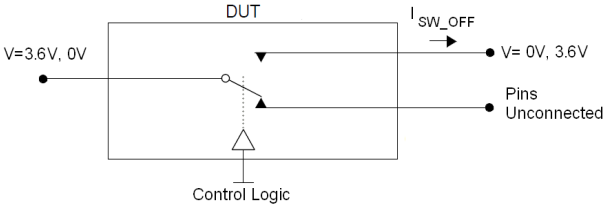


Figure 8. Off State Leakage

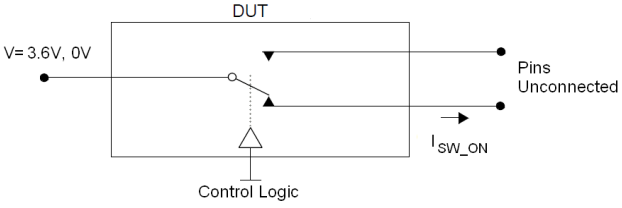


Figure 9. On State Leakage

TYPICAL OPERATING CHARACTERISTICS

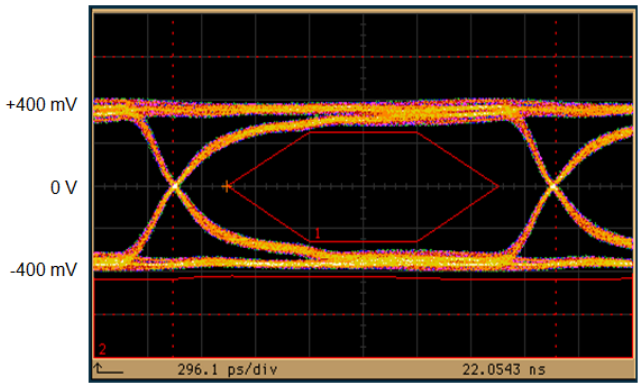


Figure 10. USB 2.0 High Speed Eye Diagram

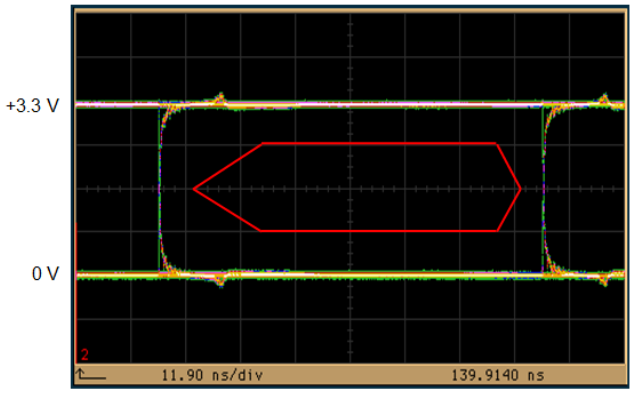


Figure 11. USB 1.1 Full Speed Eye Diagram

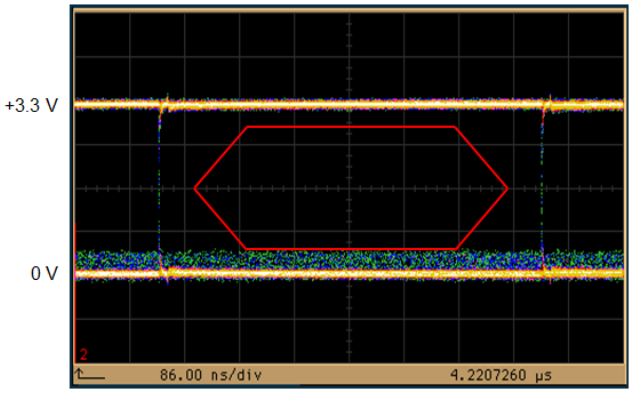


Figure 12. USB 1.0 Low Speed Eye Diagram

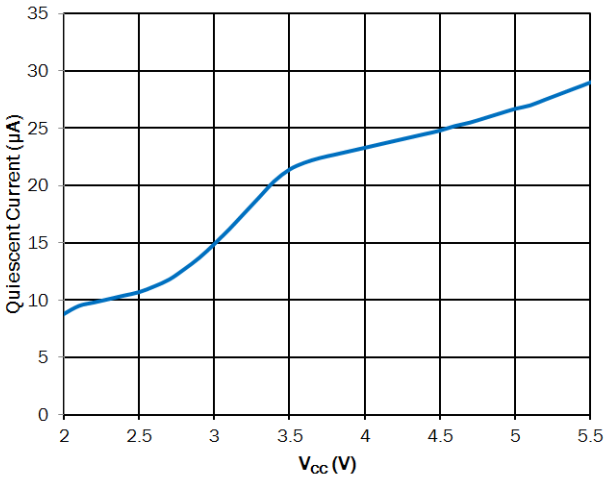


Figure 13. Product Supply Current

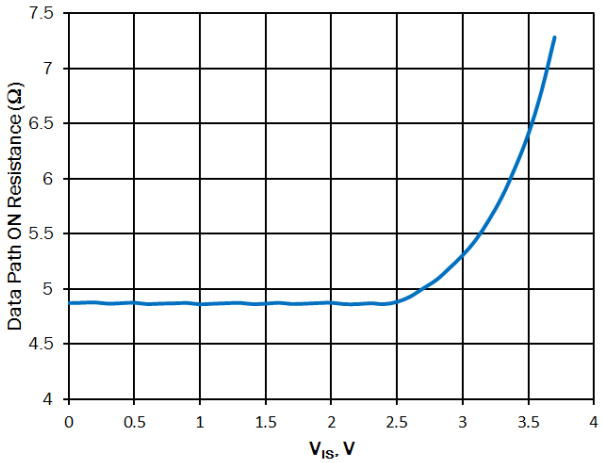


Figure 14. Data Path On Resistance

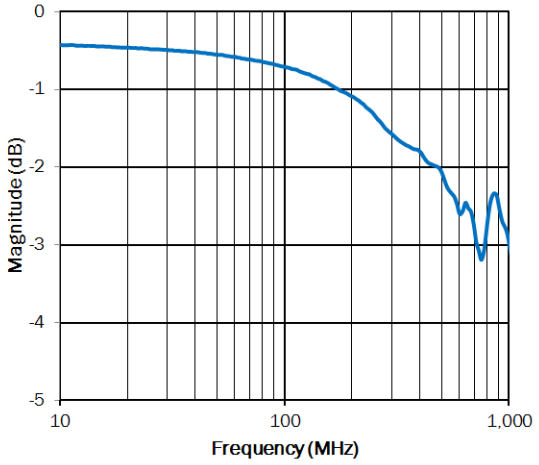


Figure 15. Data Switch Differential Insertion Loss

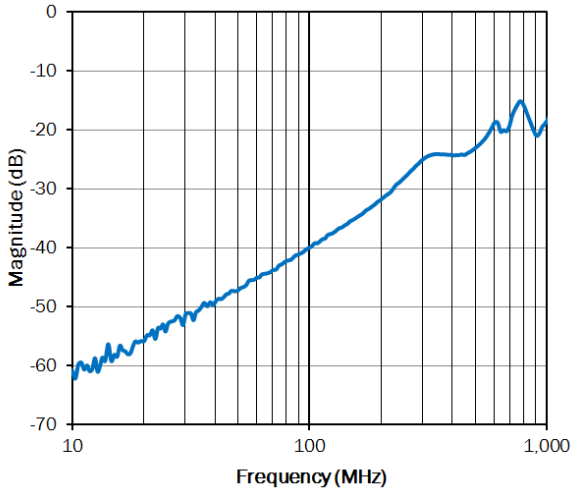


Figure 16. Data Switch Differential Off−Isolation

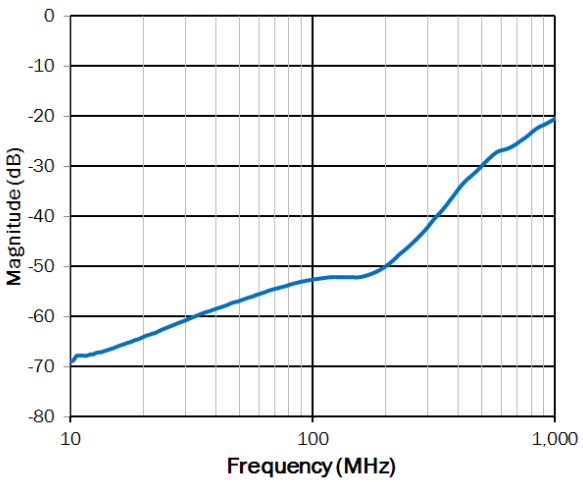


Figure 17. Data Switch Differential Crosstalk

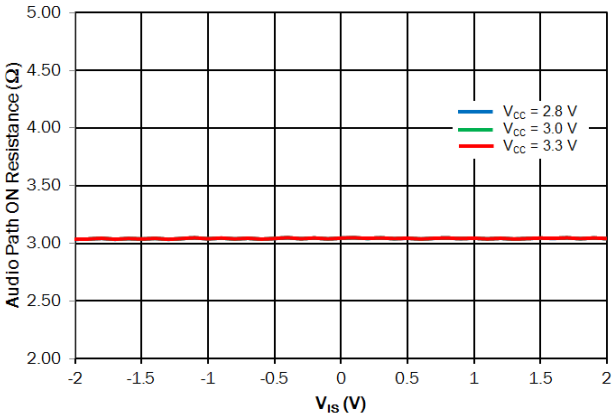


Figure 18. Audio Path On Resistance

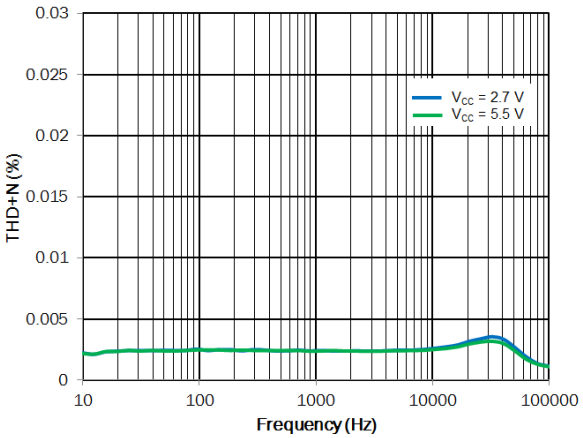
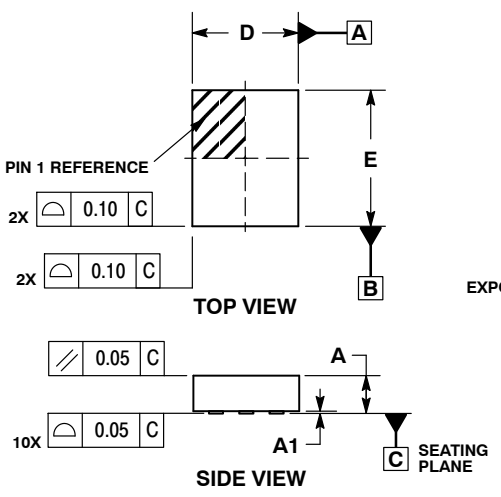
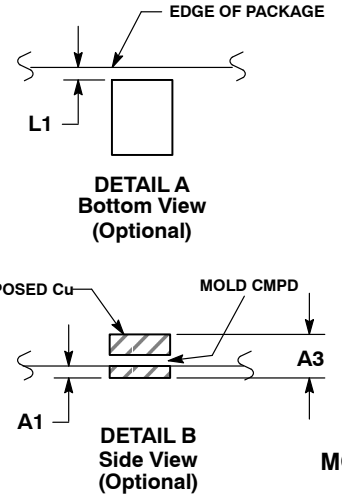


Figure 19. Audio THD

PACKAGE DIMENSIONS

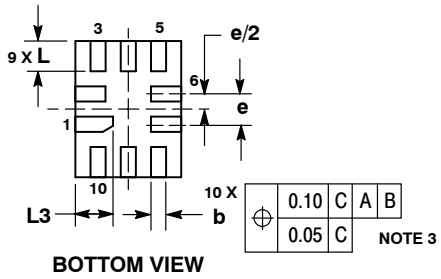
UQFN10 1.4x1.8, 0.4P
CASE 488AT
ISSUE A



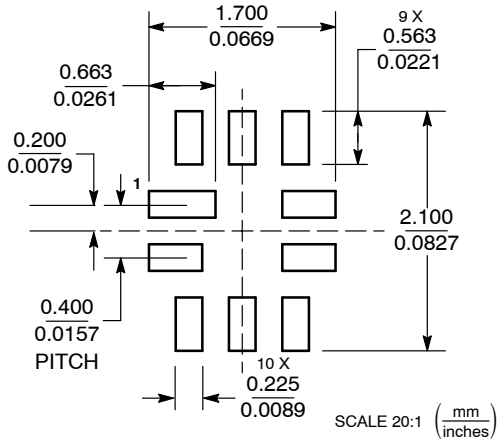


NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.45	0.60
A1	0.00	0.05
A3	0.127 REF	
b	0.15	0.25
D	1.40 BSC	
E	1.80 BSC	
e	0.40 BSC	
L	0.30	0.50
L1	0.00	0.15
L3	0.40	0.60



MOUNTING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

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LifeElectronics
Живое партнерство

ООО «ЛайфЭлектроникс» **“LifeElectronics” LLC**

ИНН 7805602321 КПП 780501001 Р/С 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 30101810900000000703 БИК 044030703

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- *Конкурентоспособные цены и скидки постоянным клиентам.*
- *Специальные условия для постоянных клиентов.*
- *Подбор аналогов.*
- *Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.*

- *Приемлемые сроки поставки, возможна ускоренная поставка.*
- *Доставку товара в любую точку России и стран СНГ.*
- *Комплексную поставку.*
- *Работу по проектам и поставку образцов.*
- *Формирование склада под заказчика.*

- *Сертификаты соответствия на поставляемую продукцию (по желанию клиента).*
- *Тестирование поставляемой продукции.*
- *Поставку компонентов, требующих военную и космическую приемку.*
- *Входной контроль качества.*
- *Наличие сертификата ISO.*

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

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- *Техническую поддержку проекта.*
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